

This listing of claims will replace all prior versions of claims in the application.

Claim 1. (currently amended) A coated substrate comprising:

- a) an organic underlayer composition coating layer on a substrate, the underlayer composition comprising ~~(i) a first resin that comprises phenol groups and (ii) a second resin that is distinct from the first resin and comprises one or more anthracene groups~~ a component that comprises aromatic and/or alicyclic groups and a component that comprises one or more chromophore groups;
- b) a photoresist composition coating layer over the underlayer composition, the photoresist comprising ~~one or more resins that comprise Si groups, phenolic groups and photoacid-labile groups~~ photoactive component and an Si-containing component.

Claims 2-21. (cancelled)

Claim 22. (currently amended) A method for forming a photoresist relief image comprising:

- a) applying an organic underlayer composition coating layer on a substrate, the underlayer composition comprising ~~(i) a first resin that comprises phenol groups and (ii) a second resin that is distinct from the first resin and comprises one or more anthracene groups~~ a component that comprises aromatic and/or alicyclic groups and a component that comprises one or more chromophore groups;
- b) applying a photoresist composition coating layer over the underlayer composition, the photoresist composition comprising a photoactive component and ~~one or more resins that comprise Si groups, phenolic groups and photoacid-labile groups~~ a photoactive component and an Si-containing component; and
- c) ~~exposing the photoresist layer to radiation having a wavelength of about 248 nm.~~

Claims 23-59. (cancelled)